High Power Dissipation SMT Chip Resistor



SC3 Series

- Tolerances to ±1%
- 3 watt rating at 70°C
- Resistance range from 1 to $100 \text{K}\Omega$
- Standard Sn/Pb and matte tin (Pb-free) terminations available

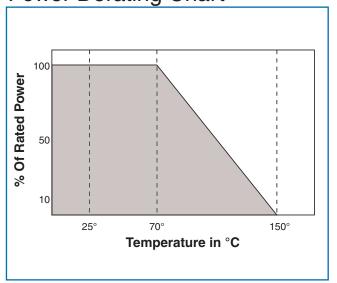


Electrical Data

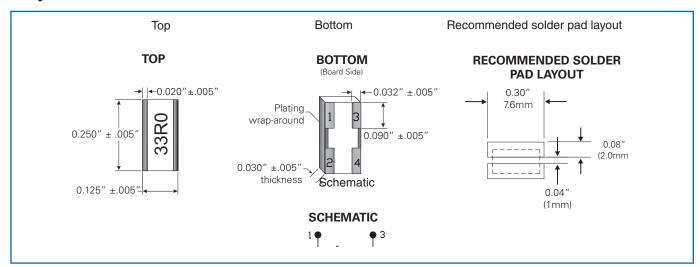
Resistance Range	1 Ω to 100K Ω	
Resistance Tolerance	±1%, ±2%, ±5%	
Temperature Coefficient	±100 ppm/°C	
Power Dissipation	3.0 Watts* @70°C	
Maximum Voltage Rating (not to exceed √P X R)	100 Volts	
Operating Temperature Range	-55°C to +150°C	
Termination	Leach-resistant nickel barrier under solder-plated wraparound	
*Note: With 1" square copper area as heat spreader		

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Power Derating Chart



Physical Data



General Note

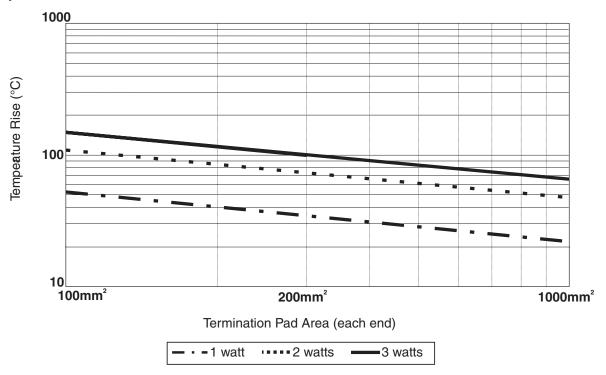
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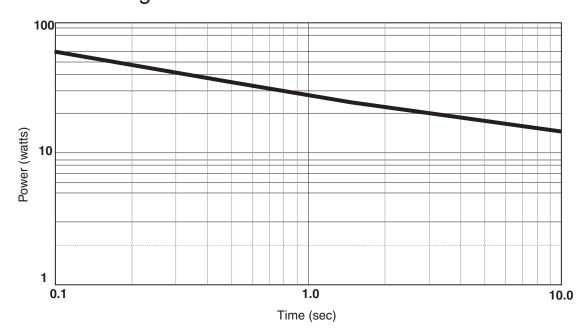
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Temperature Rise vs Pad Area



Pulse Power Rating



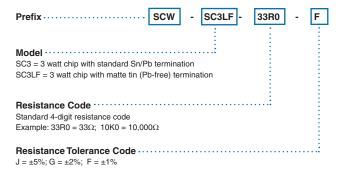
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Environmental Data

Environmental Test	Test Method	Specification
Thermal Shock	MIL-STD-202 Method 107 Condition B, -65°C + 125°C	ΔR ±0.5% + 0.01Ω
Short-time Overload	2x rated power for 5 seconds	ΔR ±0.5% + 0.01Ω
High Temperature Exposure	100 Hours, 150°C	ΔR ±0.5% + 0.01Ω
Moisture Resistance	MIL-STD-202 Method 106	ΔR ±0.5% + 0.01Ω
Load Life	Rated Power @ 70°C for 1000 hours; 1.5 hours 'on', 0.5 hours 'off'	ΔR ±1.0% + 0.01Ω
Low Temperature Operation	1 hour @ -65°C followed by Rated power for 45 minutes	ΔR ±0.5% + 0.01Ω
Resistance To Solder Heat	MIL-STD-202 Method 210 260°C, 5 seconds	ΔR ±0.25% + 0.01Ω
Solderability	MIL-STD-202 Method 208 245°C, 5 seconds	95% coverage

Ordering Data



Packaging

Available in both bulk and tape & reel.

For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.